

ABSTRACT

Each of plural semiconductor integrated circuits existing on a semiconductor wafer is provided with a function circuit (3), plural pads (4), and wirings (8) which are electrically connected to the pads (4) and contact bumps of a probe card (7), wherein at least two wirings (8a) and (8b) simultaneously contact one bump (6) in an area other than a bump area, without being in touch with each other, whereby wafer level burn-in is executed. Thereby, even when the chip area is reduced, wafer level burn-in can be carried out.